

SN1A thru SN1M

Surface Mount General

Reverse Voltage 50 to 1000V

FEATURES

- * Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- * High temperature metallurgically bonded construction
- * Capable of meeting environmental standards of MIL-S-19500
- * Diffused junction
- * 1.0 A operation at TA=75°C with no thermal runaway
- * Typical IR less than 1.0μA
- * High temperature soldering guaranteed: 260°C/10 seconds

Mechanical Data

Case: JEDEC DO-214AC, molded plastic body

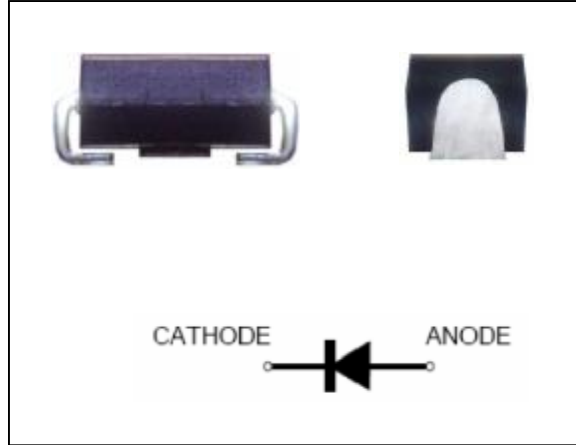
Terminals: Solderable per MIL-STD-750, Method 2026

Polarity: Color band denotes cathode end

Mounting Position: Any

Weight: 0.0023 oz., 0.075 g

Handling precaution: None



We declare that the material of product complies with ROHS requirements

1. Maximum & Thermal Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

Parameter Symbol	symbol	SN1A	SN1B	SN1D	SN1G	SN1J	SN1K	SN1M	Unit
Marking		N1A	N1B	N1D	N1G	N1J	N1K	N1M	
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RSM voltage	V_{RSM}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current 0.375" (9.5mm) lead length at $T_A = 75^\circ\text{C}$	$I_F(AV)$	1.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	25							A
Maximum thermal resistance	$R_{\theta JA}$	65							°C/W
Operating junction and storage temperature range	TJ, TSTG	-50 to +150							°C

Electrical Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

Parameter Symbol	symbol	SN1A	SN1B	SN1D	SN1G	SN1J	SN1K	SN1M	Unit
Maximum instantaneous forward voltage at 1.0A	V_F	1.1							V
Maximum DC reverse current $T_A = 25^\circ\text{C}$ at rated DC blocking voltage $T_A = 100^\circ\text{C}$	IR	5.0 50							μA
Typical junction capacitance at 4.0V, 1MHz	CJ	15.0							PF

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2. Ratings and Characteristic Curves (TA = 25°C unless otherwise noted)

Fig. 1 – Forward Current Derating Curve

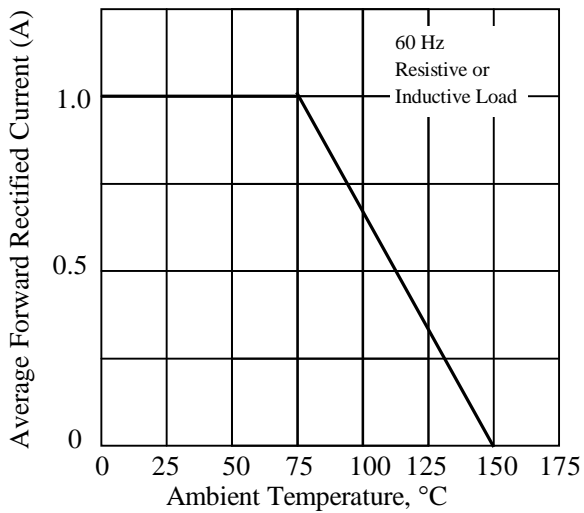


Fig. 2 – Maximum Non-repetitive Peak Forward Surge Current

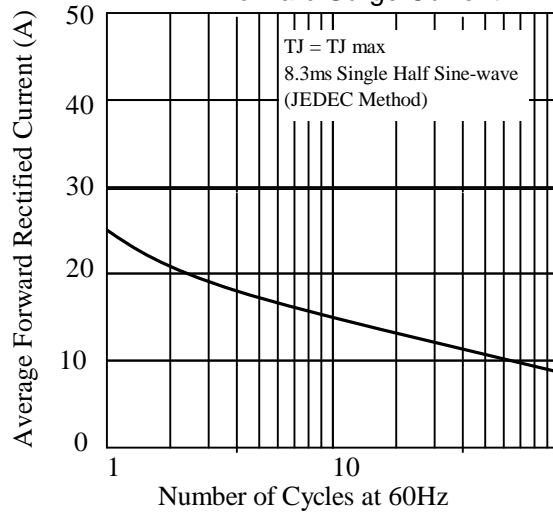


Fig 3. – Typical Instantaneous Forward Characteristics

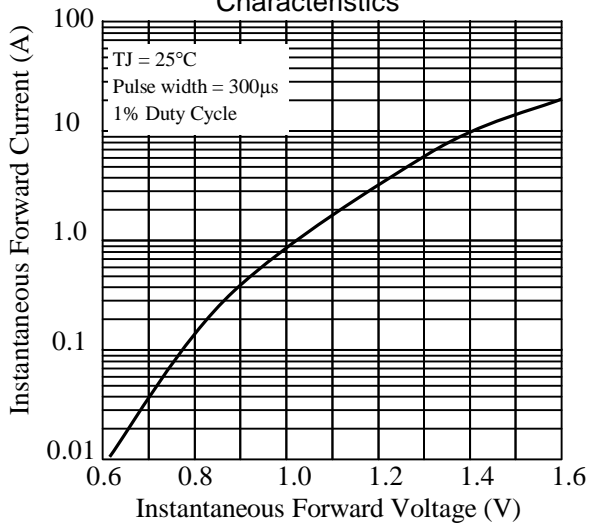


Fig 4. – Typical Reverse Characteristics

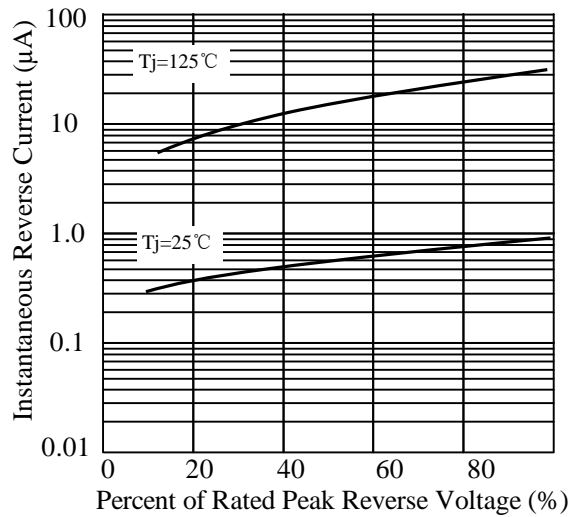


Fig 5. – Typical Junction Capacitance

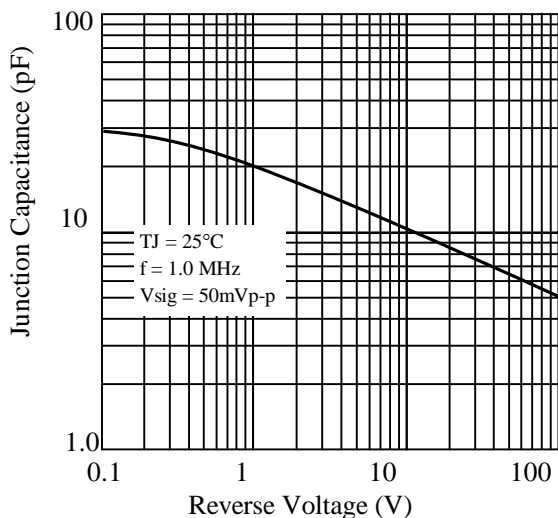
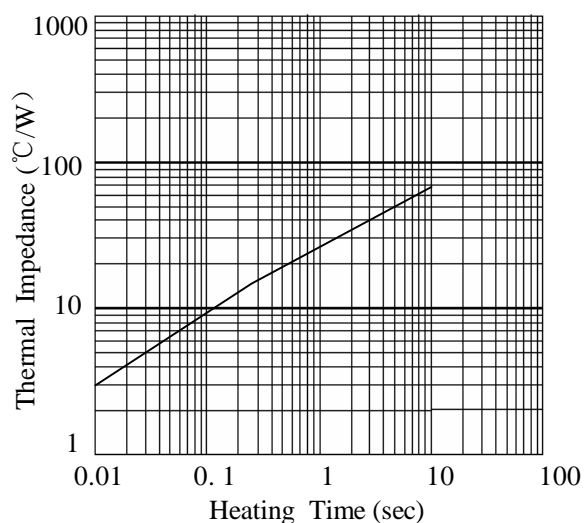
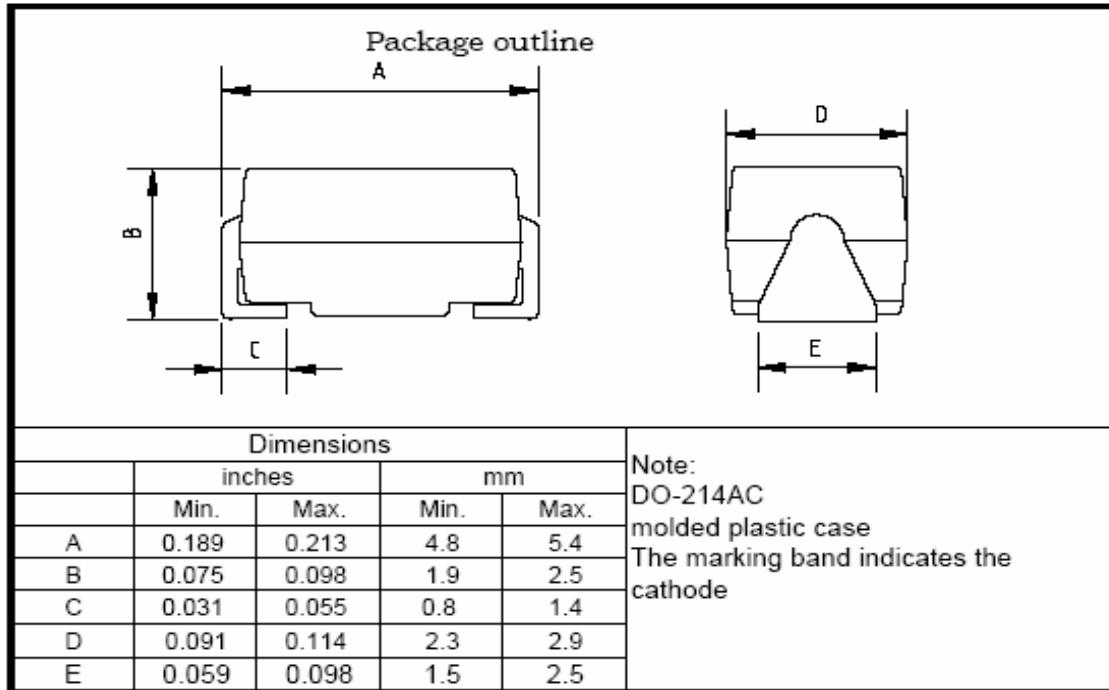


Fig 6. – Transient Thermal Impedance

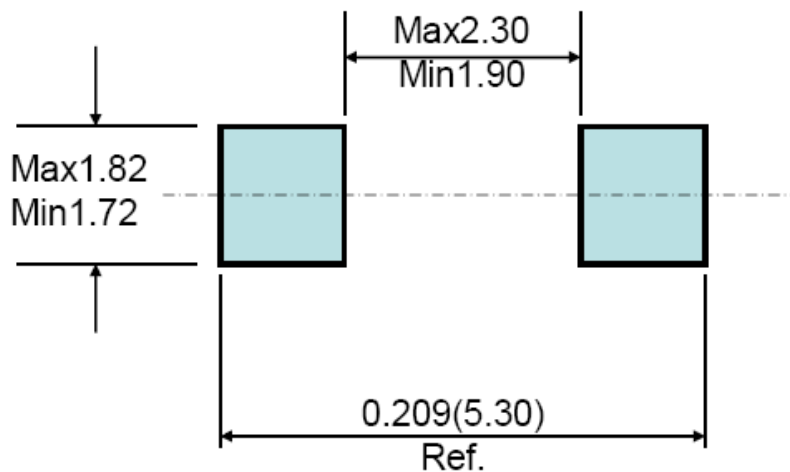


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3. dimension:



Mounting Pad Layout ---SMA

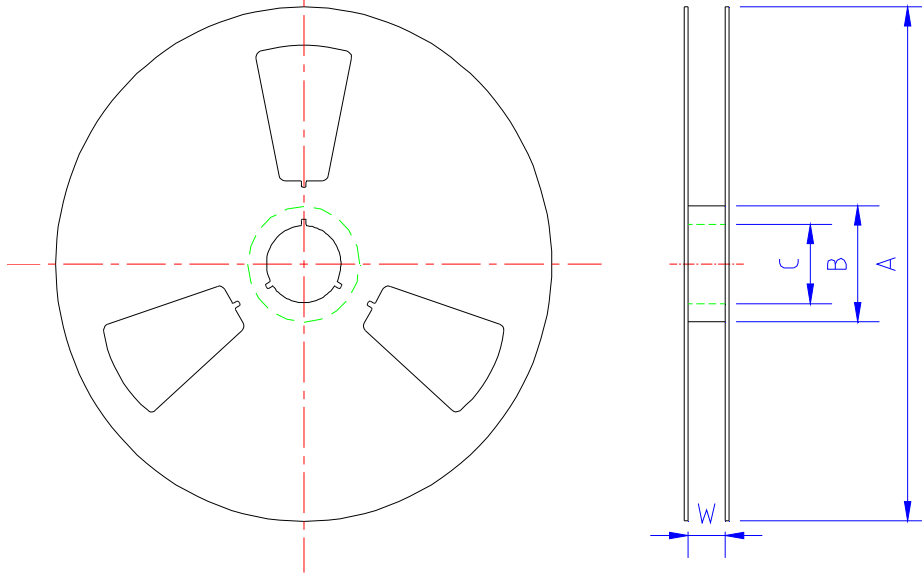


标题Title: 塑封生产线SMD产品包装规范 Packaging specification of SMD	文件编号: WI-258
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	第 2 页

SMD产品通用包装材料规格以及包装产品数量
General packaging materials spec. and quantity

1.1 卷装 reel

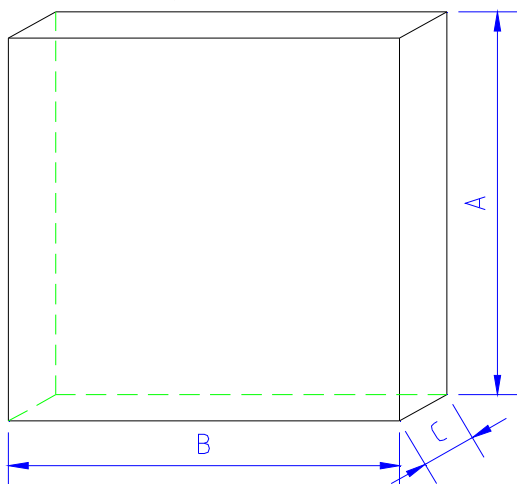
A. 卷盘规格 reel spec



单位: mm

规格	A	B	C	W	每卷数量
SMA 7"卷盘	177.0±2.0	54.0±0.5	13.0±0.5	13.2±0.2	2K
SMA13"卷盘	330.0±2.0	75.0±0.5	13.0±0.5	13.2±0.2	5K
SMB13"卷盘	330.0±2.0	75.0±0.5	13.0±0.5	13.5±0.5	3K
SMC13"卷盘	330.0±2.0	75.0±0.5	13.0±0.5	17.0±0.5	3K

B. 13"卷盘内盒 inner box



单位: mm

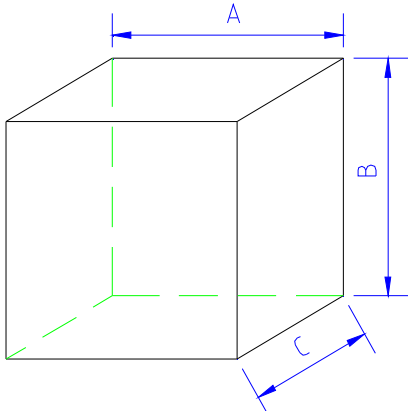
	A	B	C
尺寸	335±5.0	335±2.0	40±1.0

按以上包装方式, 产品包装数量: quantity

规格	每盒数量
SMA13"卷盘	10K
SMB13"卷盘	6K
SMC13"卷盘	6K

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C. 7"卷盘盒 box



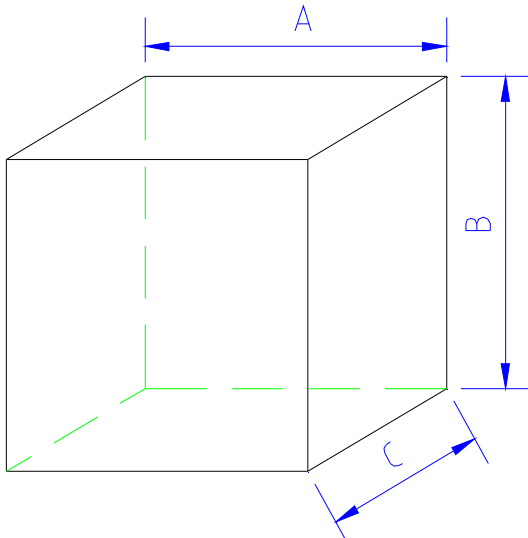
单位: mm

	A	B	C
尺寸	188±2.0	188±2.0	138±2.0

按以上包装方式, 产品包装数量: quantity

	每盒数量
7"卷盘	16K

D. 卷盘外箱 reel carton



单位: mm

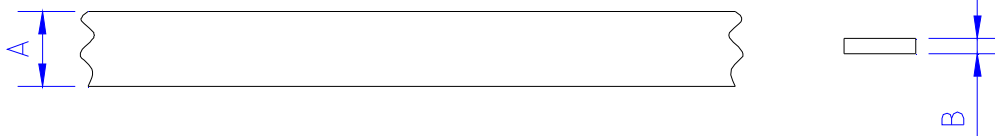
	A	B	C
尺寸	350±2.0	340±2.0	350±2.0

按以上包装方式, 产品包装数量:

规格	每箱数量
SMA 7"卷盘	80K
SMA13"卷盘	80K
SMB13"卷盘	48K
SMC13"卷盘	36K

1.2 编带规格 tape spec

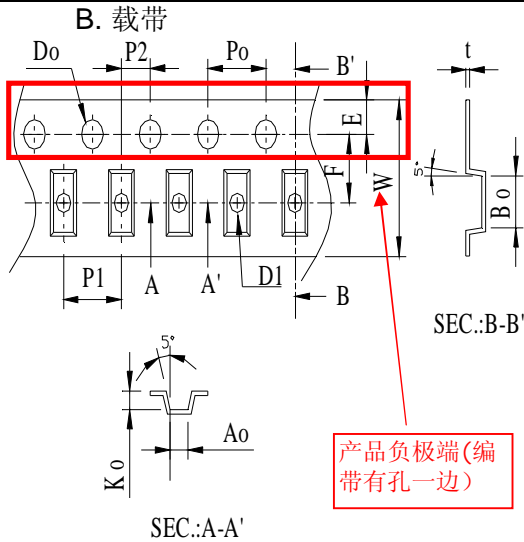
A. 盖带 Cover tape



单位: mm

	A	B
SMA	9.30±0.10	0.068±0.005
SMB		
SMC		

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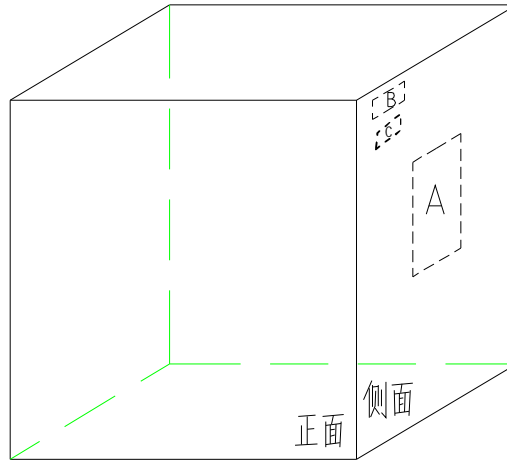
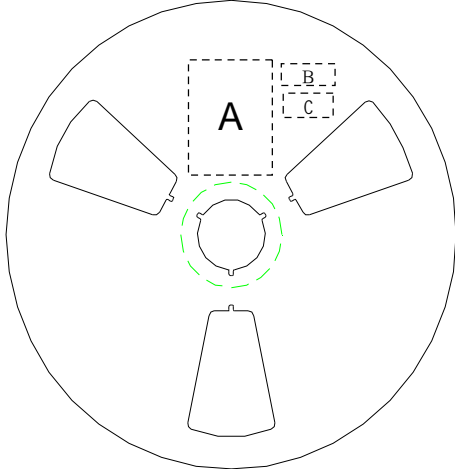
类型	SMA	SMB	SMC
W	12±0.3	12±0.3	16±0.3
P1	4±0.1	8±0.1	8±0.1
E	1.75±0.1	1.75±0.1	1.75±0.1
F	5.5±0.05	5.5±0.05	7.5±0.05
D0	1.55±0.05	1.55±0.05	1.55±0.05
D1	1.5±0.1	1.55±0.05	1.55±0.05
P0	4±0.1	4±0.1	4±0.1
P2	2±0.05	2±0.05	2±0.05
10P0	40±0.2	40±0.2	40±0.2
A0	2.79±0.1	3.8±0.1	6.05±0.1
B0	5.33±0.1	5.4±0.1	8.31±0.1
K0	2.36±0.1	2.45±0.1	2.54±0.1
T	0.25±0.05	0.25±0.05	0.25±0.05

2、SMD产品通用包装规范 General spec of SMD

5.2.1国内客户domestic

A. 7"卷盘reel

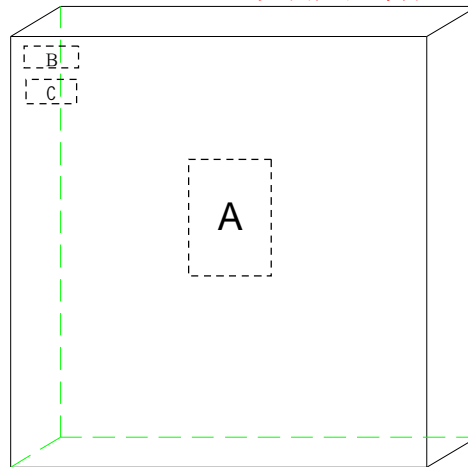
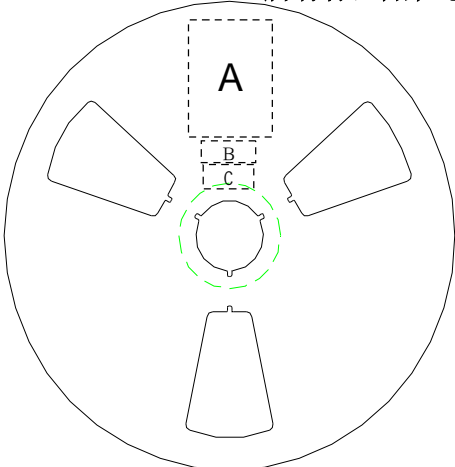
所有标签贴在卷盘负极 all the label on cathode side



A处:贴LRC标签; B处:贴ROHS标签 C处:贴无卤标签 HF label

B. 13"卷盘

所有标签贴在卷盘负极 all the label (无卤产品才贴HF only)




A处:贴LRC标签; B处:贴ROHS标签 C处:贴无卤标签 (无卤产品才贴HF only)

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C. 标签要求label spec:

LRC标签label

型号 TYPE	*****	← LRC产品型号 type
数量(只) QTY(PCS)	*****	← 产品数量 quantity
批号 LOT	*****	← 产品批号 LOT
日期 DATE	*****	← 产品生产日期 date
检验员: CHECKER		

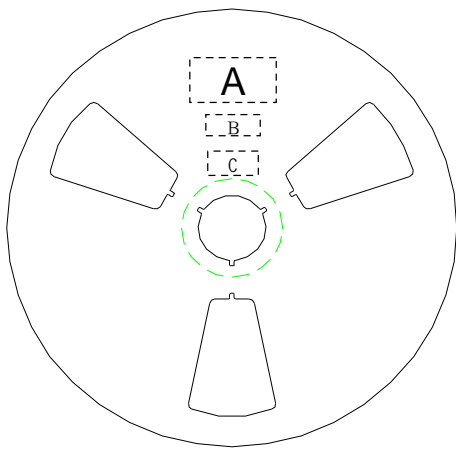
ROHS标签



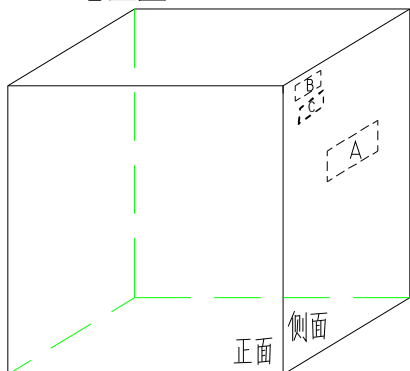
无卤标签 HF label



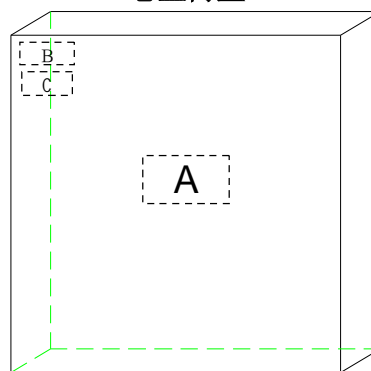
2.2 国外客户 overseas 所有标签贴在卷盘负极 all the label on cathode side



7"卷盘盒 inner box



13"卷盘内盒inner box



A处:贴LRC标签;

B处: 贴ROHS标签

C处: 贴无卤标签HF label

(无卤产品才贴HF only)

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LRC标签label

TYPE:*****	← LRC产品型号
MARK:*****	← 印字型号
Q'TY:*****	← 产品数量
DATE:*****	← 产品生产日期

ROHS标签



无卤标签 HF label



注意事项NOTE:

- 13"卷盘内盒装好产品,需用热缩膜包装;13"reel'inner box must be packed by shrink film
- 所有编带产品卷装完成后,用白色胶带将编带粘牢;
every tape after packing, must be fixed by white adhesive tape

3.1产品出厂检验报告 testing report of the OQC

每批出货时,需要附上出厂检验报告 every lot must with test report

3.2尾箱

同一编码每批次只允许出现一个尾数箱,对于尾数物料,须用缓冲材料对空余部分填充好,保证物料在受到一定的外作用力下不发生明显移动,且物料间无碰撞。

The same coding is only one ending for each batch box materials for the mantissa to be good filled with cushioning material.

SN1A thru SN1M

4. Update Record

版次	更新记录	更新作者	更新日期
1	第一版	周杰	2010-3-23
2	增加包装规范和焊盘尺寸	周杰	2011-9-26